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RF360 Europe GmbH

Data sheet

Micro-acoustic filter GPS L5

Series/type:	B8884
Ordering code:	B39122B8884P810
Date:	September 20, 2019
Version:	2.3

DCN: 80-PA243-340 Rev. C

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1 Application

- Low-loss RF GNSS L5 filter
- Usable passbands: 20.46 MHz for GPS L5
- Very low insertion attenuation
- High out of band selectivity
- Filter impedance 50 Ω
- Unbalanced to unbalanced operation
- No matching network required for operation at 50 Ω

2 Features

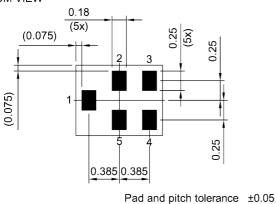
- Package size 1.1 mm × 0.9 mm
- Package height 0.45 mm (max.)
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)



Figure 1: Picture of component with example of product marking.

3 Package

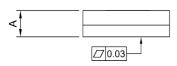
BOTTOM VIEW

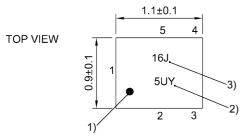


4 Pin configuration

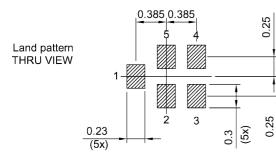
- ∎ 1 Input
- 4 Output
- 2, 3, 5 Ground

SIDE VIEW





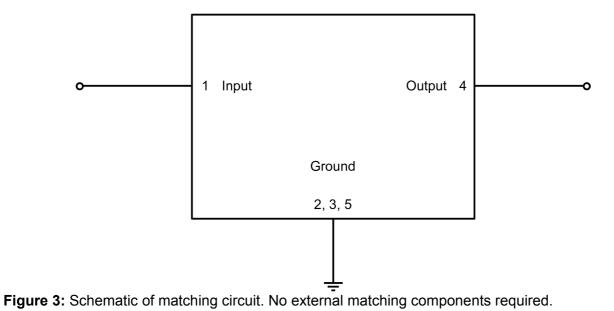
- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



Landing pad tolerance -0.02**Figure 2:** Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 18).



5 Matching circuit



Please read **Cautions and warnings** and **Important notes** at the end of this document.

6 Characteristics

Temperature range for specification	$T_{_{\rm SPEC}}$	= −30 °C +85 °C
Input terminating impedance	Z _{IN}	= 50 Ω
Output terminating impedance	Ζ _{ουτ}	= 50 Ω

Characteristics				min. for $T_{\rm SPEC}$	typ. @ +25 °C	max. for $T_{\rm SPEC}$	
Center frequency			f _c		1176.45	—	MHz
Insertion Loss			α				
	1166.22 1186.68	MHz		—	1.0	1.6	dB
	1166.22 1186.68	MHz		—	1.0	1.4 ¹⁾	dB
VSWR			VSWR				
@ input port	1166.22 1186.68	MHz		—	1.5	2.0	
@ output port	1166.22 1186.68	MHz		—	1.6	2.0	
Attenuation			α				
	698 748	MHz		40	45	_	dB
	777 798	MHz		40	45	—	dB
	807 915	MHz		40	45	—	dB
	925 960	MHz		40	45	_	dB
	1427 1511	MHz		32	40	—	dB
	1626.5 1660.5	MHz		24	32	—	dB
	1695 1850	MHz		33	40	—	dB
	1850 1980	MHz		38	46	—	dB
	2000 2200	MHz		38	44	—	dB
	2300 2400	MHz		37	46	—	dB
	2400 2483	MHz		35	46	—	dB
	2500 2690	MHz		33	40	—	dB
	3400 3800	MHz		22	30	—	dB
	5150 5925	MHz		20	26	—	dB

Valid for temperature T = +25 °C.

1)

7 **Maximum ratings**

Storage temperature	$T_{\rm STG}^{2)} = -40 \ ^{\circ}{\rm C} \ +85 \ ^{\circ}{\rm C}^{1)}$	
DC voltage	$ V_{\rm DC} = 5.0 \rm V (max.)^{3}$	
ESD voltage	$V_{\rm ESD}^{4)}$ = 50 V (max.)	Machine model.
	$V_{\rm ESD}^{5)}$ = 300 V (max.)	Human body model.
	V _{ESD} ⁶⁾ = 600 V (max.)	Charged device model.
Input power @ Pin 1 or Pin 4:		
1166.221186.68 MHz	P _{IN} = 10 dBm	Continuous wave for 5000 h @ 55 °C.
669960 MHz	P _{IN} = 15 dBm	Continuous wave for 5000 h @ 55 °C.
14272690 MHz	P _{IN} = 15 dBm	Continuous wave for 5000 h @ 55 °C.

1) Extended upperlimit: 96h@125°C acc. to IEC 60068-2-2 Bb.

2) Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

3) 168h Damp Heat Steady State acc. IEC 60068-2-67 Cy.

4) According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

5)

According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse. According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses. 6)



8 Transmission coefficient

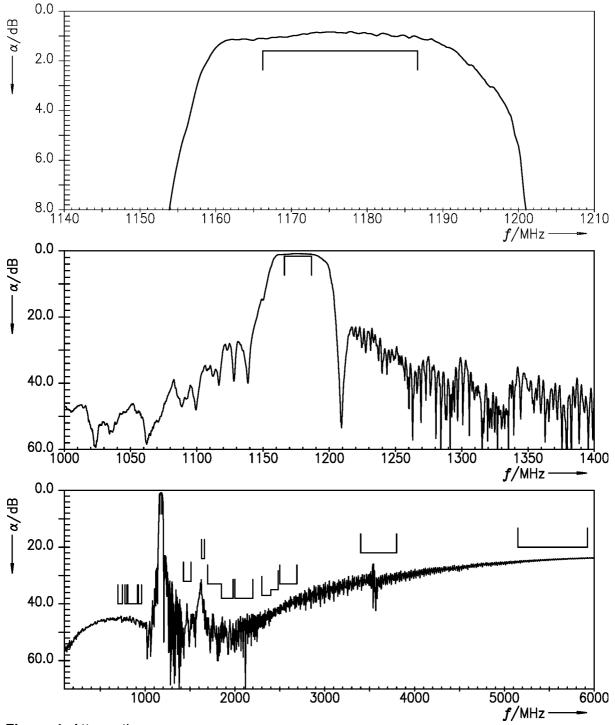


Figure 4: Attenuation.



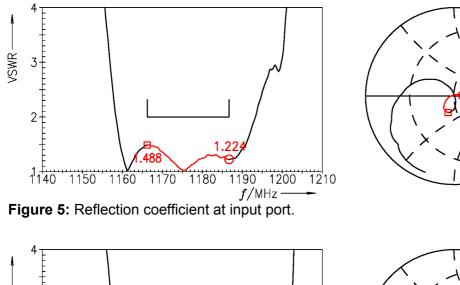
□ = 1166.2 O = 1186.7

□ = 1166.2 O = 1186.7

Z_{IN}=50 Ω

Z_{OUT}=50 Ω

9 Reflection coefficients



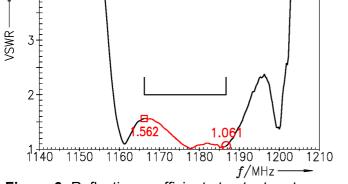


Figure 6: Reflection coefficient at output port.



10 Packing material

10.1 Tape

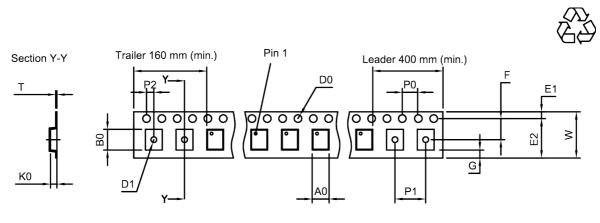




Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.02±0.05 mm
B ₀	1.22±0.05 mm
D ₀	1.55±0.05 mm
D ₁	0.55±0.1 mm
E ₁	1.75±0.1 mm

E₂ 6.25 mm (min.) F 3.5±0.05 mm G -K₀ 0.6±0.05 mm P₀ 4.0±0.1 mm

P_1	2.0±0.1 mm
P ₂	2.0±0.05 mm
Т	0.25±0.03 mm
W	8.0+0.3/-0.1 mm

Table 1: Tape dimensions.



10.2 Reel with diameter of 180 mm

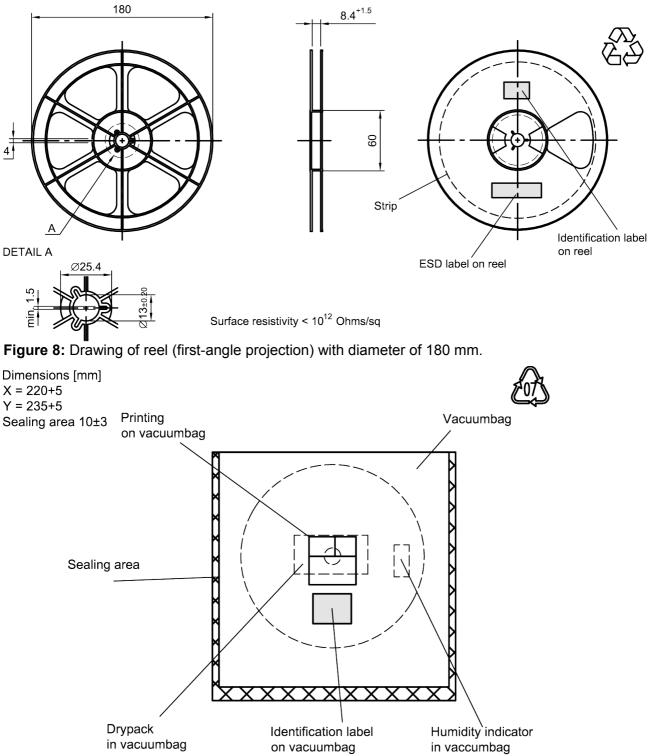


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

Please read **Cautions and warnings** and **Important notes** at the end of this document.

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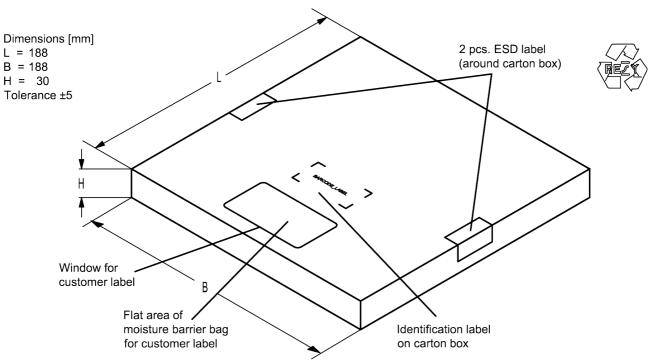
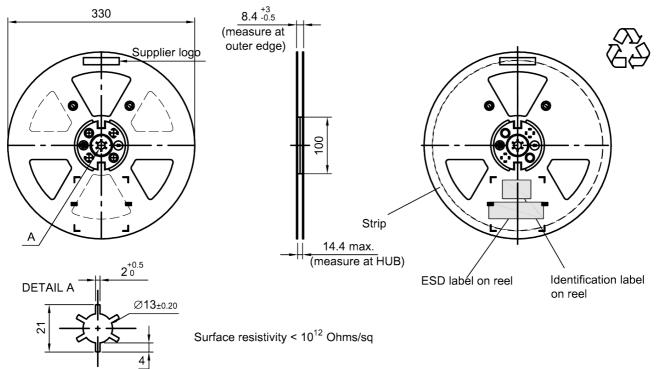
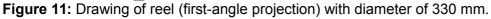


Figure 10: Drawing of folding box for reel with diameter of 180 mm.

10.3 Reel with diameter of 330 mm







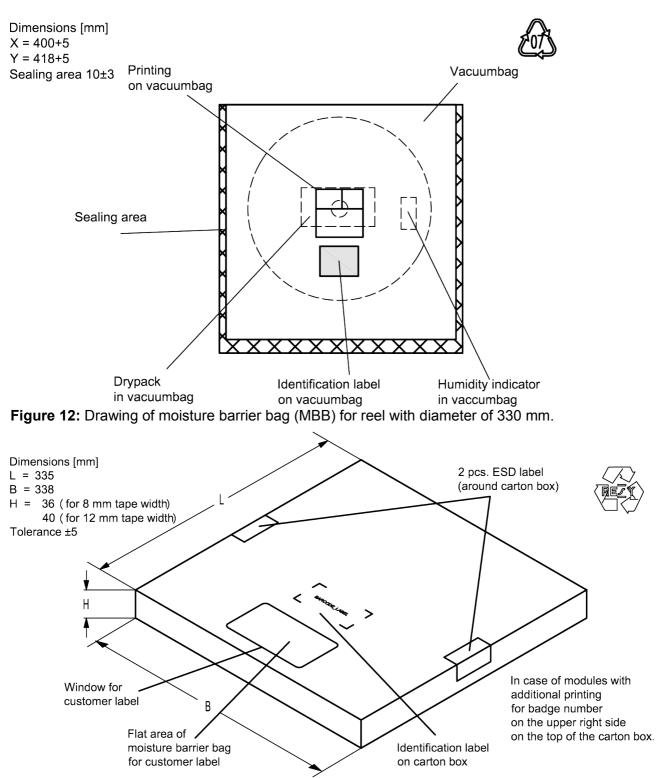


Figure 13: Drawing of folding box for reel with diameter of 330 mm.

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11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, is encoded by a special BASE32 code into a 3 digit marking.		e.g., B3xxxxE g.	3 <u>1234</u> xxxx,
Example of decoding 16J 1 x 32 ² + 6 x	type number marking on device => 32 ¹ + 18 (=J) x 32 ⁰ =		in decimal code. 1234 1234
	oduct type B8884 is 8NM.		-

Lot number:

The last 5 digits of the lot number,e.g.,**12345**,are encoded based on a special BASE47 code into a 3 digit marking.12345,

Example of decoding lot number marking on device **5UY**

5 x 47² + 27 (=U) x 47¹ + 31 (=Y) x 47⁰

	in decimal code.
=>	12345
=	12345

Adopted BASE32 code for type number			
Decimal	Base32	Decimal	Base32
value	code	value	code
0	0	16	G
1	1	17	Н
2	2	18	J
3	3	19	K
4	4	20	М
5	5	21	N
6	6	22	Р
7	7	23	Q
8	8	24	R
9	9	25	S
10	А	26	Т
11	В	27	V
12	С	28	W
13	D	29	Х
14	E	30	Y
15	F	31	Z

Adop	Adopted BASE47 code for lot number		
Decimal	Base47	Decimal	Base47
value	code	value	code
0	0	24	R
1	1	25	S
2	2	26	Т
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	В	35	f
12	С	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	V
17	Н	41	١
18	J	42	?
19	К	43	{
20	L	44	}
21	М	45	<
22	N	46	>
23	Р		

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
<i>T</i> > 220 °C	30 s to 70 s
<i>T</i> > 230 °C	min. 10 s
<i>T</i> > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T _{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

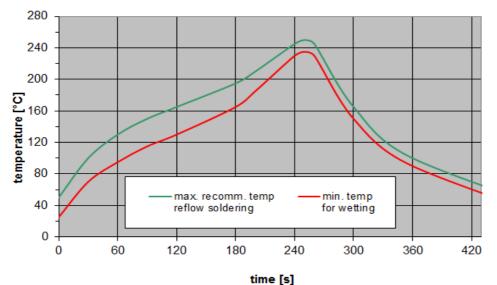


Figure 14: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Ordering codes and packing units

Ordering code	Packing unit
B39122B8884P810	15,000 pcs
B39122B8884P810S 5	5,000 pcs
B39122B8884P810W 5	5,000 pcs

 Table 4: Ordering codes and packing units.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under https://rffe.qualcomm.com/.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.



15 Important notes

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